

Title (en)
SINTERED TUNGSTEN ALLOY

Title (de)
GESINTERTE WOLFRAMLEGIERUNG

Title (fr)
ALLIAGE DE TUNGSTÈNE FRITTÉ

Publication
EP 2789708 A4 20151014 (EN)

Application
EP 12856450 A 20121127

Priority
• JP 2011267845 A 20111207
• JP 2012080565 W 20121127

Abstract (en)
[origin: EP2789708A1] There is provided a flat plate-like sintered tungsten alloy that can be molded into a complex shape by press working or forge processing. The flat plate-like sintered tungsten alloy contains 85% by mass or more and 98% by mass or less of W, 1.4% by mass or more and 11% by mass or less of Ni, and 0.6% by mass or more and 6% by mass or less of at least one substance selected from the group consisting of Fe, Cu and Co, wherein an elongation percentage of the flat plate-like sintered tungsten alloy in a planar direction is 20% or more.

IPC 8 full level
C22C 27/04 (2006.01); **B22F 3/24** (2006.01); **C22C 1/04** (2006.01); **C22F 1/00** (2006.01); **C22F 1/18** (2006.01)

CPC (source: EP US)
B22F 3/24 (2013.01 - EP US); **B22F 5/006** (2013.01 - EP US); **C22C 1/045** (2013.01 - EP US); **C22C 27/04** (2013.01 - EP US);
C22F 1/02 (2013.01 - EP US); **C22F 1/18** (2013.01 - EP US); **Y10T 428/12014** (2015.01 - EP US)

Citation (search report)
• [A] CN 101230427 A 20080730 - UNIV CENTRAL SOUTH [CN]
• [A] JANG ET AL: "Study on the solid-phase sintering of the nano-structured heavy tungsten alloy powder", JOURNAL OF ALLOYS AND COMPOUNDS, ELSEVIER SEQUOIA, LAUSANNE, CH, vol. 434-435, 29 March 2007 (2007-03-29), pages 367 - 370, XP022008679, ISSN: 0925-8388, DOI: 10.1016/J.JALLCOM.2006.08.215
• See references of WO 2013084749A1

Cited by
EP3229268A4; CN106756379A; RU2623566C1

Designated contracting state (EPC)
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DOCDB simple family (publication)
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DOCDB simple family (application)
EP 12856450 A 20121127; JP 2012080564 W 20121127; JP 2012080565 W 20121127; JP 2013548184 A 20121127; JP 2013548185 A 20121127; US 201214363401 A 20121127